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TI Metal **plating** of electric conducting copper or **copper alloy wire** for coil feeding and solderability
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PA Furukawa Electric Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 02204919	A2	19900814	JP 1989-23334	19890201
AB	The wire is electroplated with Ni and then with Ag or Cu at 0.5-0.2d and 5-1.5 .mu.m (d is outer diam. of the wire), resp., for easy coil feeding and good solderability. The electroplated wire shows solder-wetting time 0.1-0.5 s, wire core-melting time 5-25 s, elec. cond. (IACS) 83-100%, and tensile strength 50-85 kg/mm2.				